

EAST - [09329586.wsp.1]

File View Edit Tools Window Help

Search Find Replace

Drafts  
BRS: plated  
Pending  
Active  
L1: (4626494) gold au  
L2: (1111042) lead leadframe (lead adj frame)  
L3: (2069493) ic (integrated adj circuit) chip die dice semiconductor  
L4: (2682) 1 same 2 same plated  
L5: (1117) 4 same 3  
L6: (763) 5 and package  
L7: (516) 6 and solder  
Failed  
Saved  
(96375) ((bendable flexible moveable) with (frame container supporter))  
(1808) ((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (frame))  
(51221) ((bendable flexible moveable) with (frame))  
(1235) ((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (frame))  
(432) (((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (frame)) and ((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (frame))  
(96375) ((bendable flexible moveable) with (frame container supporter))  
(1808) ((bendable flexible moveable) with (frame container supporter)) and ((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (frame))  
(1235) ((bendable flexible moveable) with (frame container supporter)) and ((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (frame))  
(432) (((bendable flexible moveable) with (frame container supporter)) and ((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (frame))  
Favorites  
Tagged (0)  
UDC  
Queue  
Trash

USPAT  
Default operator: OR  
6 and solder

BRS Item ESR Item Change Text HTML

	g	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval C	Inventor	S	C	P	3	2
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6368893 B1	20020409	12	Method of fabricating semiconductor device	438/106	438/114; 438/127		Tani, Takeyuki et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6368704 B1	20020409	13	Conductive paste of high thermal conductivity and	428/323	252/500; 252/514		Murata, Satoshi et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6356778 B1	20020319	10	Semiconductor package comprising lead frame with	438/123	257/666; 438/124		Shinohara, Toshiaki	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6350772 B2	20020319	15	Semiconductor package having semiconductor element	438/106	257/696		Miyoshi, Tadayoshi	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
5	<input type="checkbox"/>	<input type="checkbox"/>	US 6351996 B1	20020305	11	Hermetic packaging for semiconductor pressure	73/706			Nasiri, Steven S. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
6	<input type="checkbox"/>	<input type="checkbox"/>	US 6348729 B1	20020219	10	Semiconductor chip package and manufacturing method	257/691	257/666; 257/668		Li, Sai Man et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
7	<input type="checkbox"/>	<input type="checkbox"/>	US 6341962 B1	20020129	8	Solderless grid array connector	439/66	439/71		Sinclair, William Y.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
8	<input type="checkbox"/>	<input type="checkbox"/>	US 6339191 B1	20020115	67	Prefabricated semiconductor chip carrier	174/52.4	257/692		Crane, Jr., Stanford W. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
9	<input type="checkbox"/>	<input type="checkbox"/>	US 6338994 B1	20020115	27	Resin-molded semiconductor device, method for	438/123	257/666; 438/124		Minamio, Masanori et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
10	<input type="checkbox"/>	<input type="checkbox"/>	US 6337522 B1	20020108	11	Structure employing electrically conductive	257/734	257/673; 257/737		Kang, Sung Kwon et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
11	<input type="checkbox"/>	<input type="checkbox"/>	US 6337445 B1	20020108	14	Composite connection structure and method of	174/260	174/257; 228/130.22		Abbott, Donald C. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>